



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hui et al.

Serial No.: 09/916,197

Filed: July 27, 2001

For: METHOD FOR ENCAPSULATING
INTERMEDIATE CONDUCTIVE
ELEMENTS CONNECTING A
SEMICONDUCTOR DIE TO A
SUBSTRATE AND SEMICONDUCTOR
DEVICES SO PACKAGED

Confirmation No.: 7070

Examiner: J. Vigushin

Group Art Unit: 2827

Attorney Docket No.: 2269-4712US
(99-1054.00/US)

Notice of Allowance Mailed:

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

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Commissioner for Patents
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Sir: